GTAz, GTz, GDAz GDz Dual side Inline AOI

 $\sqrt{}$  Dual side inline full featured inspection

 $\sqrt{}$  In height adjustable optical head



Featuring industry leading GTAz head and optional high

Compensate for PCB warp and adapt to tall component and

## In-Line DUAL side Automatic Optical Inspection systems

	clearance GDAz head
$\sqrt{}$ High Speed 90Fps thunderbolt main camera and USB Cameras side cameras	The latest generation of high speed, high quality cameras No capture card requirements.
$\sqrt{}$ Synchronized top and bottom inspection	Top and bottom heads are linked to allow parallel inspection cycles
$\sqrt{}$ Multi-color 4 angle lighting with Line Source Coaxial Lighting Meniscus Profiler	ghting and reliable solder joint meniscus and pad surface analysis (to find meniscus and paste printing defects)
<ul> <li>✓ Inspects:</li> <li>— Components: SMT &amp; THT (missing, type, polaritext, colors, etc.)</li> <li>— Component Height and Coplanarity</li> <li>— Solder Paste and CIP (Components in Paste; post New York)</li> <li>— Soldering: Post Reflow, Post Wave, Selective, THT solder inspection</li> </ul>	pre-reflow)
$\sqrt{}$ Flexible classification and reporting scenarios	integrate AOI efficiently in your existing operations and factory lay-out
√ Line Sourced DOAL(Direct On Axis Lighting) coaxial lig system with high resolution Telecentric Optics	
$\sqrt{}$ Low Noise Large CCD High Speed 24 bit Color Camer	find defects easier including printing defects on Gold or Cu plated PCB's
$\sqrt{}$ Synthetic Imaging and Spectral Analysis	powerful algorithms to achieve an optimal balance between defect detection and false reject levels in shortest time
$\sqrt{}$ Triple use of side camera's	Use for automatic inspection, classification and repair
√ Prototype mode for 1st off inspection	program in minutes to verify your production line is set-up correctly before starting full production



sandwich assemblies

# Enwertpectur GTAZ GDAZ

### **Hardware and Software Features**





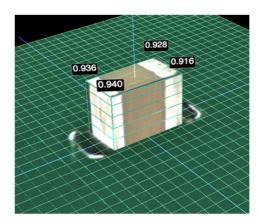








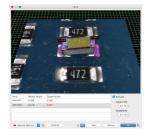




#### Revolutionary 3D imaging On GTAz head

True Stereoscopic imaging using 9 cameras. Full colour 3D allows the ability to actually see the side of components rather than extruded 2D images. Using the addition of a 4th LED white light



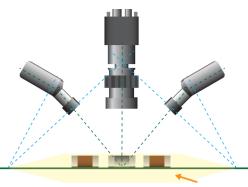


#### The perfect combination of 3D and 2D inspection

Height, tilt and coplanarity measurement. Pin Height measurement Component Presence Absence, Polarity, Value, Angle, Offset, Colour, Extra part detection, Solder ball detection, Solder profile analysis and short detection. The thickness of chip capacitors in combination with colour makes a more reliable inspection when checking chip capacitors value.

## Unique 3D Stereoscopic Vision

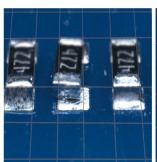
Utilizing the full 9 cameras of the MEK camera head. The image differential are merged and a vectorised map of the component is created. Then analyzed based on the programmers applied tolerances. The vectorized map of the components removes the minor imperfection of the component surface giving

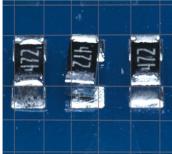


more accurate measurement of height and surface angle of the component with reduced chance of false readings.

### 8x Angular Side Sensors (Only available for GTAz and GDAz models)

Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database





Without Shift&Tilt

Shift&Tilt

### Shift & Tilt Side View lenses

Distortion free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics

#### The GDAz and GDz

Heads provide an extended over board clearance of 60 mm (2.4") Allowing for taller THT component inspection on an inline system

#### Sixteen possible head combinations

18 Camera, 9 Top and 9 Bottom Cameras to 2 Camera Single top and Bottom Cameras. The D22X BTL is the Ultimate in platform flexibility

	GTAz	30mm clearance, Passive 3D SMT
	GDAz	60mm Clearance SMT and THT
	GTz	35mm Clearance SMT and THT
	GDz	60mm+ Clearance SMT and THT



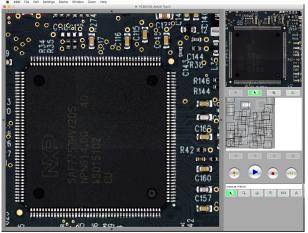






# Enwertpectur GTAZ GDAZ

### Hardware and Software Features — Continued

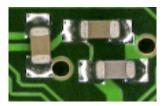


#### Double size FOV (Field of view)

Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

#### Large pixel image capturing sensor

18.8µm² pixel size — less noise — smooth and detailed image— great dynamic range





High dynamics sensor

Conventional sensor

#### In Height Adjustable Optical Head

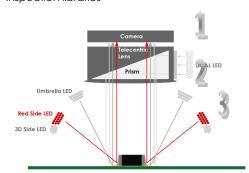
In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components Inspection of "Sandwich" assemblies without need of jigs and multiple inspections

#### Omnidirectional multi angle, multi color LED lighting

Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints

#### **SMT Solder Inspection**

Full solder profiling and histogram algorithm analysis. Simple prebuilt solder inspection libraries





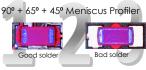


45° side light



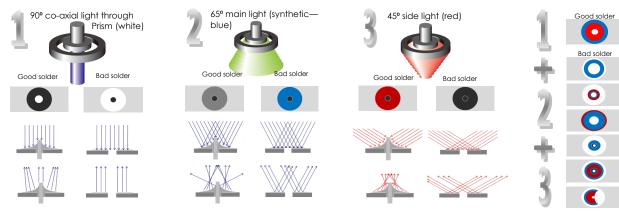
65° main light





#### **THT Solder Inspection**

Scalable inspection points for the wide variety of Solder land shapes and pin sizes, Bridge and solder ball detection algorithms.



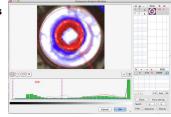


Powerful algorithms for solder bridge detection Simple and scalable



Histogram Analysis algorithms Condition based decision Tolerances can be set tightly Close to zero false alarms





Dedicated algorithms for solder balls detection

## **Inline**



## **GTAz+GDAz**

350BTL, 550BTL

In-Line Series Specifications	PowerSpector GTAz/GDAz 350BTL	PowerSpector GTAz/GDAz 550BTL
Maximum PCB Size	350x250mm (13.8"x9.8")	550x550mm (21.6"x21.6")
Characteristics	, , , , , , , , , , , , , , , , , , , ,	(2.10.2.10)
Product type	Automatic Optical Inspector	
In-line/Off-line	In-Line	
Camera movement	X + Y Direction	
PCB movement		
Parts inspection	Stationary during inspection Presence, Polarity, Offset, Correctness, Soldering, Height	
Printing/paste inspection		
mage Processing	Offset, Smearing, Bridges, Uniformity Synthetic Imaging, Spectral Analysis, Greyscale limits	
mage Parameters	Brightness, Hue, Satu	
Camera type	Digital color Thunderbo	
Camera Field Of View/Resolution		
Lens	38.5x38.5mm/18.75µm or 19.5x19.5mm/10µm	
LC113	Telecentric lens with built in prism for DOAL Lighting  Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced DOAL	
Lighting system	(Diffused On Axis Ligh	nting (Coaxial))
Specifications		
Minimum inspection component size	ponent size 01005" (0.4x0.2mm) (10µm resolution)	
Positioning accuracy	Pixel related Feed	dback Loop
Component clearance (top)	GTAz 30mm (1.2") GD	Az 60 mm (2.4")
Side Cameras	8x Digital color USB 3.0 Vision in 45/45 orientation	
Z-Axis movement range	30mm (1.2")	
Component clearance (bottom)	30mm (1.2") with GTAz bottom camera or 60mm (2.4") GDAz bottom camera	
Maximum PCB Size	350x250mm (13.8" x 9.8")	550x550mm (21.6" x 21.6")
Movement speed	720mm/s	
nspection capacity typical	2750ppm	
Electrical requirements 100-240		/ 330W
Conveyor		
Conveyor belt speed		
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm	
PCB Clamping	Top Justified, Ruler Blade, Top & Ed	ge Clamping, Sensor Stopper
Minimum board size	50x50mm (2.0" x 2.0")	
Board thickness	0.6-4mm (24mils - 79mils)	
Interfacing		
Control PC type	Apple Mac Mini	or iMac x2
Control interface	SMEMA (cor	veyer)
Data interface	USB and Thur	nderbolt
Programming Interface	CSV Centroid file (Placement file)	
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Wind	ows 7/8/10) (option)
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)	
General		
Operating temperature	15-30 deg. C(60-90 deg. F)	
Operating humidity	15-80 % RH	
	W740 x D786 x H1236	W1078 x D1320 x H1317
External size	(29.1" x 30.9" x 48.7")	(42.4" x 52" x 51.8")
Weight	240kg (397lbs)	400kg (529lbs)

 ${\small \textit{Mek Europe reserves the right to change the design and specifications without notice. @ \textit{Mek Europe BV}, 2016.}$ 

Represented/Distributed by:



# **Inline**



## GTz+GDz

350BTL, 550BTL

In-Line Series Specifications	PowerSpector GTz/GDz 350BTL	PowerSpector GTz/GDz 550BTL
Maximum PCB Size	350x250mm (13.8'x9.8")	550x550mm (21.6"x21.6")
Characteristics	(1010 %) 10 )	Coordooniiii (2110 X2110 )
Product type	Automatic Optical Inspector	
In-line/Off-line	In-Line	
Camera movement	X + Y Direc	
PCB movement	Stationary during	
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height	
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity	
Image Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits	
mage Parameters	Brightness, Hue, Saturation via Filters	
Camera type	Digital color Thunderbol	
Camera Field Of View/Resolution	38.5x38.5mm/18.75µm or 19.5x19.5mm/10µm	
Lens	Telecentric lens with built in p	·
Lighting system	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced DOA (Diffused On Axis Lighting (Coaxial))	
Specifications		
Minimum inspection component size	01005" (0.4x0.2mm)(10	Oµm resolution)
Positioning accuracy	Pixel related Feedback Loop	
Component clearance (top)	GTAz 30mm (1.2") GD	Az 60 mm (2.4")
Side Cameras	NA	
Z-Axis movement range	30mm (1.2")	
Component clearance (bottom)	35mm (1.2") with GTz bottom camera or 60mm+ (2.4") GDz bottom camer	
Maximum PCB Size	350x250mm (13.8" x 9.8")	550x550mm (21.6" x 21.6")
Movement speed	720mm	
Inspection capacity typical	2750ppm	
Electrical requirements	100-240 VAC / 330W	
Conveyor		, 656
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)	
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm	
PCB Clamping	Top Justified, Ruler Blade, Top & Edg	•
Minimum board size	50x50mm (2.0	
Board thickness	0.6-4mm (24mil	s - 79mils)
Interfacing		
Control PC type	Apple Mac Mini	or iMac x2
Control interface	SMEMA (con	veyer)
Data interface	USB and Thun	derbolt
Programming Interface	CSV Centroid file (PI	acement file)
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windo	ows 7/8/10) (option)
3rd party Interfacing (MES) & Data Storage		
General		
Operating temperature	15-30 deg. C(60-90 deg. F)	
Operating humidity	15-80 % RH	
	W740 x D786 x H1236	W1078 x D1320 x H1317
External size	(29.1" x 30.9" x 48.7")	(42.4" × 52" × 51.8")
Weight	240kg (397lbs)	400kg (529lbs)

Mek Europe reserves the right to change the design and specifications without notice. © Mek Europe BV, 2016

Represented/Distributed by:

Mek Americas LLC





Mek Europe BV Polluxstraat 2b 5047 RB Tilburg, Netherlands T +31 40 7114111 info@mek-europe.com, www.mek-europe.com

